

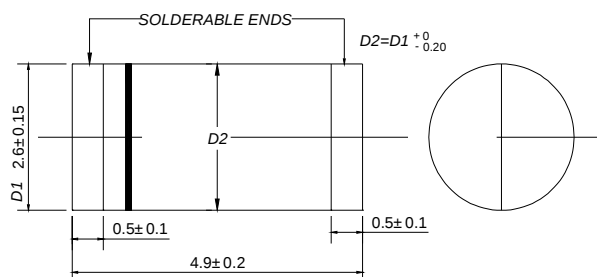


DL4001 THRU DL4007

SURFACE MOUNT RECTIFIERS

REVERSE VOLTAGE: 50 - 1000 V CURRENT: 1.0 A

DO - 213AB



Dimensions in millimeters

FEATURES

Glass passivated device
Ideal for surface mounted applications
Low leakage current
Metallurgically bonded construction

MECHANICAL DATA

Case: JEDEC DO-213AB, molded plastic over passivated chip
Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Weight: 0.0046 ounces, 0.116 gram
Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

MDD Catalog Number		DL 4001	DL 4002	DL 4003	DL 4004	DL 4005	DL 4006	DL 4007	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current $T_A=75$	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	30							A
Maximum forward voltage at 1.0A	V_F	1.1							V
Maximum DC reverse current @ $T_A=25$ at rated DC blocking voltage @ $T_A=125$	I_R	5.0 50							μA
Typical junction capacitance (NOTE 1)	C_j	15							pF
Typical thermal resistance (NOTE 2)	$R_{j\theta L}$	20							/W
Typical thermal resistance (NOTE 3)	$R_{j\theta A}$	50							/W
Operating temperature range	T_j	- 55 --- + 175							
Storage temperature range	T_{STG}	- 55 --- + 175							

NOTES: 1. Measured at 1.0MHz and applied average voltage of 4.0V DC.

2. Thermal resistance junction to lead, 6.0 mm² copper pads to each terminal.

3. Thermal resistance junction to ambient, 6.0 mm² copper pads to each terminal.

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RATINGS AND CHARACTERISTIC CURVES DL4001 THRU DL4007

FIG. 1 - TYPICAL FORWARD CURRENT DERATING CURVE

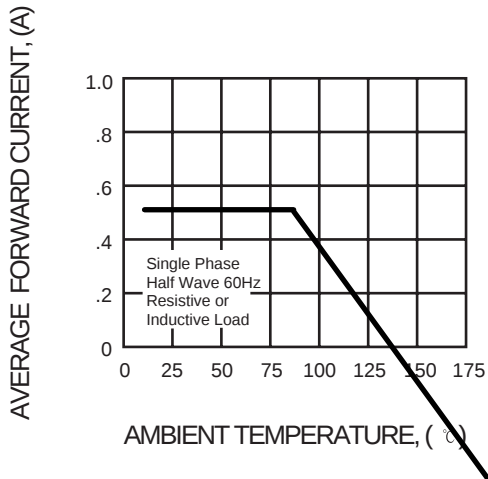


FIG. 2 - MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

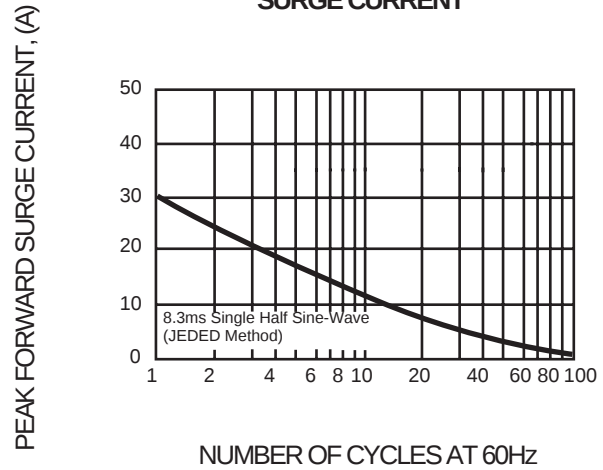


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

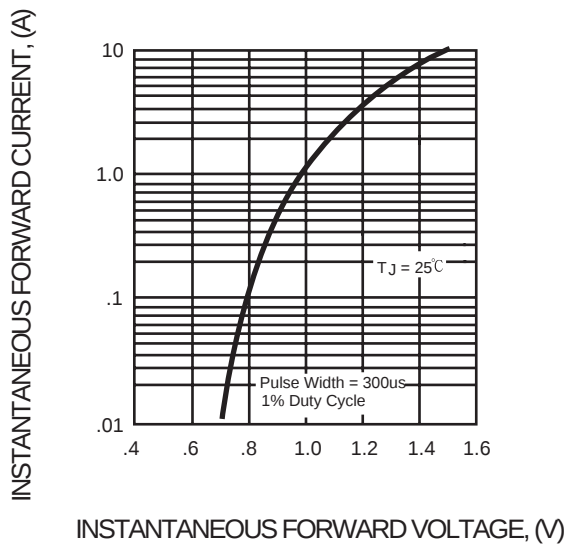


FIG. 4 - TYPICAL REVERSE CHARACTERISTICS

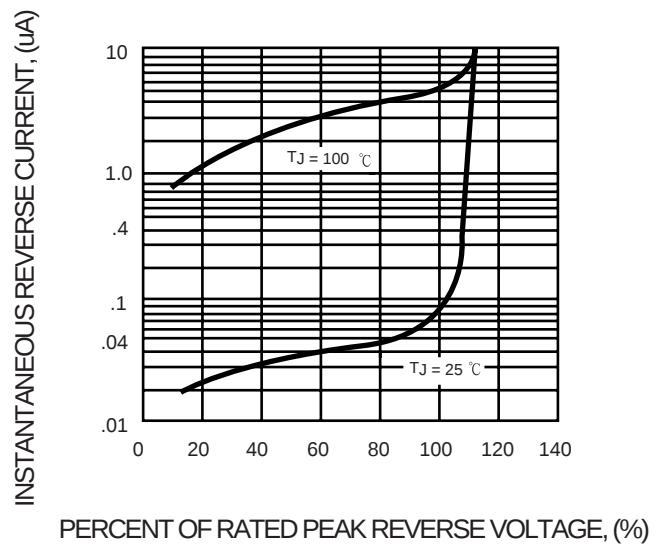
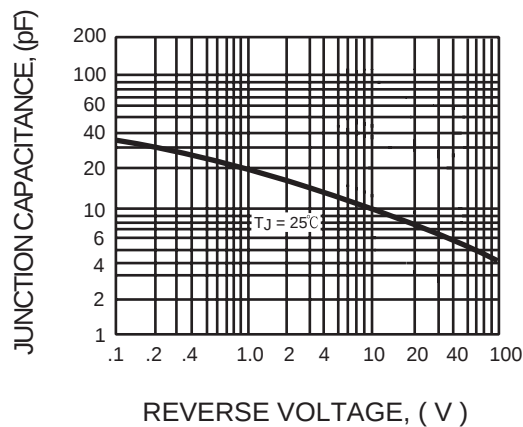


FIG. 5 - TYPICAL JUNCTION CAPACITANCE



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